**AMENDMENTS TO THE SPECIFICATION:**

The specification has been amended to reflect the following changes:

Please replace the second full paragraph beginning on page 1, line 12 and ending on page 1, line 22, with the following paragraph:

Recent electronic ~~products~~products have been improved to meet the requirement for higher performance and further size reduction. Accordingly, high density mounting techniques are developed for electronic parts to be incorporated in those small electronic products. To attain such high density mounting, semiconductor chips are often designed as bare chips that are surface-mountable on the wiring board (flip-chip mounting). For mounting semiconductor chips with high density, use is often made of multilayer wiring boards, which are suitable for multi-pin type chips.

Please replace the first full paragraph beginning on page 3, line 5 and ending on page 3, line 14, with the following paragraph:

However, when a large semiconductor chip is mounted on a wiring board, the stress reduction by the under filler alone is often insufficient to ensure desirable reliability. This is because the difference in thermal expansion between the semiconductor chip and the wiring board increases as the chip becomes larger, whereby an unduly great stress can be produced at the connecting portions between the chip and the wiring board. The same problem can occur ~~to~~in a case where a large semiconductor wafer or chip is mounted on a probe card.